TR0636E-20027

IT3D(M)-300S-BGA (57) BGA Shearing Force TEST REPORT

APPROVED

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[1] Objective

To evaluate BGA shearing force by comparing Initial state and Post 3500 thermal cycle in accordance with IPC-9701.

[2] Specimens

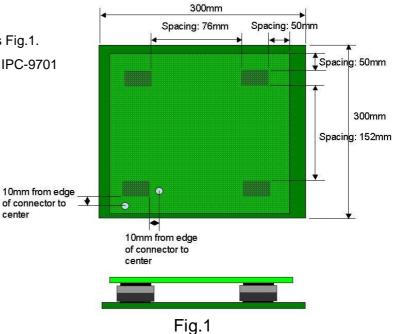
Туре	Product	Assembly	State	# of specimens
Type_1	IT3D-300S-BGA (57)	Virgin	Initial	3
Type_2	IT3D-300S-BGA (57)	Reworked	Initial	3
Type_3	IT3D-300S-BGA (57)	Virgin	Post	3
			3500 cycles	
Type_4	IT3D-300S-BGA (57)	Reworked	Post	3
			3500 cycles	

Remarks

*Type_3, Type_4 are assembled as Fig.1.

*The test board design is based on IPC-9701 specification.

*Thickness of the PCB: 3.3mm



[3] Test period

2007-09-12 From: To 2008-01-18

[4] Test Equipment

Test equipment	Model	Manufacture
Insertion and withdrawal force tester	AG-IS	Shimazu

center

BGA shearing force

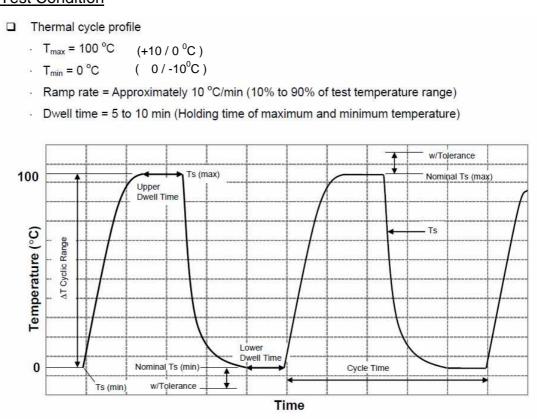
1. Requirements

The failure mode for the sheared balls shall be either bulk solder failure or copper pad lift-off.

Intermetallic failure is unacceptable.

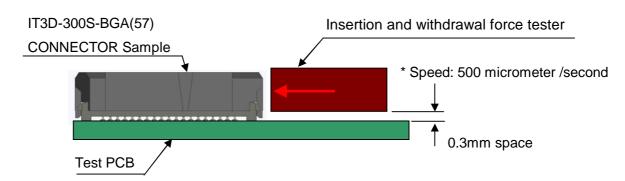
2. Conditions

2-1 Test Condition



☐ Test cycle: 3500 cycles

2-2 BGA Shearing Force



4. Results

4-1 BGA Shearing Force

UNIT: KN

No.	Type-1	Type-2	Type-3	Type-4
State	Initial		Post 3500 thermal cycles	
Assembly	Virgin	Reworked	Virgin	Reworked
1	1.22	1.18	1.21	1.13
2	1.18	1.16	1.13	0.91
3	1.25	1.18	1.13	1.11
MAX	1.25	1.18	1.21	1.13
MIN	1.18	1.16	1.13	0.91
AVG	1.22	1.17	1.16	1.05

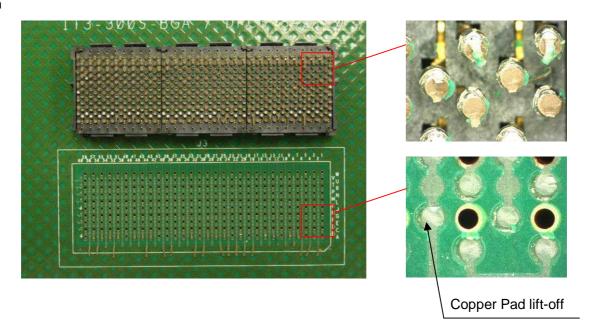
4-2 Failure Mode

No intermetallic failure was found in all specimens. Copper pad lift-off was found in the sheared area.

Details are shown in the following pages.

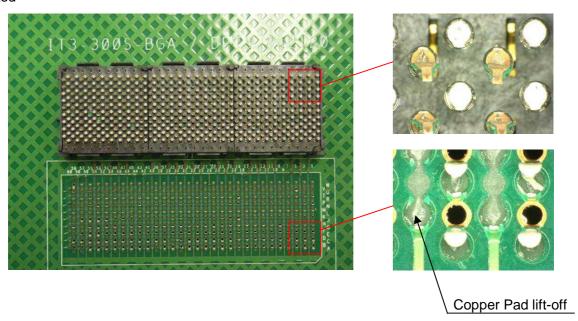
Type-1 (Initial)

Virgin



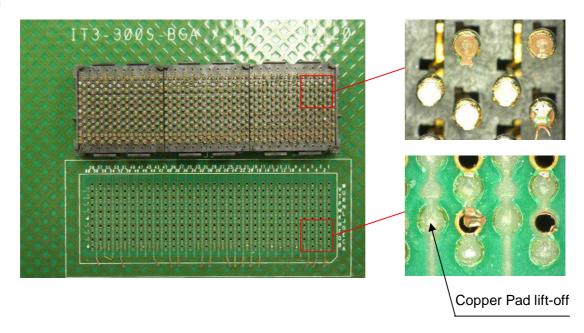
Type-2 (Initial)

Reworked



Type-3 (Post 3500 thermal cycles)

Virgin



Type-4 (Post 3500 thermal cycles)

Reworked

